

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

*Paul H. A.*

In re application of :  
Morio GAKU et al. : Attn: APPLICATION BRANCH  
Serial No. [NEW] : Docket No. 2000-1503A  
Filed October 31, 2000 :

COPPER-CLAD BOARD SUITABLE FOR :  
MAKING HOLE WITH CARBON DIOXIDE :  
GAS LASER, METHOD OF MAKING HOLE :  
IN SAID COPPER-CLAD BOARD AND :  
PRINTED WIRING BOARD COMPRISING :  
SAID COPPER-CLAD BOARD :

THE COMMISSIONER IS AUTHORIZED  
TO CHARGE ANY DEFICIENCY IN THE  
FEE FOR THIS PAPER TO DEPOSIT  
ACCOUNT NO. 23-0975.

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents  
Washington, DC 20231

Sir:

In the interest of compact prosecution and to reduce PTO filing fees, please amend the present application as follows:

IN THE CLAIMS:

Claim 22, amend as follows:

22. (Amended) A printed wiring board according to claim 19, wherein the double-side-treated copper foil [recited in claim 5] is a product formed by attaching a B-staged thermosetting resin composition layer to a surface opposite to the surface having the metallic -treatment layer and heating the resultant set under pressure to make an alloy of the metal of the metallic-treatment layer with the copper, and is disposed on at least one surface of an internal board such that the copper foil side faces outside, the resultant set is laminate-formed under heat and pressure to obtain a copper-clad board, and the upper surface of the copper-clad board is directly irradiated with a carbon dioxide gas laser having

*a*